

8. (Twice Amended) The semiconductor structure of Claim 1 or 7 wherein the semiconductor structure comprises a 3-D memory array, wherein the 3-D memory array comprises a plurality of memory cells arranged in a plurality of layers stacked vertically above one another in a single chip.

REMARKS

I. Introduction

Independent Claims 1 and 7 were rejected under 35 U.S.C. § 103(a) as being unpatentable over the proposed combination of Hu et al., Wilson et al., Nakayama et al., and Spinelli et al. Because these references, alone or in combination, do not teach each and every element recited in the claims, Applicants respectfully request reconsideration and withdrawal of the rejections.

Applicants appreciate the willingness of Examiner Magee to conduct a telephone interview with the undersigned attorney on May 2, 2003. Applicants faxed a copy of this Amendment to the Examiner, and the issues raised in this Amendment were discussed during the telephone interview. It was agreed that the cited figure and embodiment in Hu et al. do not teach the elements asserted to be taught in the Office Action. The Examiner agreed that, if a new Office Action is warranted citing different figures and embodiments in Hu et al., the new Office Action would be made non-final. The Examiner also agreed that the elements recited in dependent Claim 8 were not shown in the applied art and stated that he would do an additional search.